AMENDMENTS TO THE CLAIMS

The following is a complete, marked-up listing of revised claims with a status identifier in parenthesis, underlined text indicating insertions, and strike through and/or double-bracketed text indicating deletions.

LISTING OF CLAIMS

1. (Currently Amended) ~~Assembly process of~~ A process for assembling at least one electronic component including ~~sensibly~~ flat conductive areas that are connected to conductive tracks placed on ~~the~~ a surface of a ~~generally~~ flat insulating ~~support called a~~ substrate, ~~characterized by the following steps~~ comprising:

- placing the substrate on a work surface, the face including conductive tracks being oriented upwards,
- placing the electronic component into a cavity of the substrate situated in a zone including the conductive tracks, the conductive areas of the electronic component coming into contact with the corresponding conductive tracks of the substrate, and
- applying a layer of insulating material which extends concurrently ~~at the same time~~ on the electronic component and at least on the ~~a substrate~~ zone of the substrate surrounding said electronic component, wherein the conductive areas of the electronic component and the conductive tracks of the substrate are in contact to achieve an electric connection via a pressure of application of the insulating material layer on the electronic component, and configured to rub together when repeated stressed are exerted on the substrate ~~in such a way that the electric~~

~~connection between the conductive areas and conductive tracks is ensured by the pressure of the insulating layer on the component~~.

2. (Currently Amended) The process ~~Process~~ according to claim 1, wherein the electronic component is made up of a chip provided with contacts on one of ~~its~~ the faces of the chip, said contacts being set off on a conductive film constituting the contact areas that extend the contacts of the chip, the opposite face of the chip being coated by an insulating material.

3. (Currently Amended) The process ~~Process~~ according to claim [[1]] 2, wherein the layer of insulating material is made up of a first substrate including a cavity into which the electronic component is inserted, ~~by its~~ the coated face of the electronic component being inside the cavity, the contact areas of said electronic component connecting with corresponding conductive areas of a second substrate placed on the work surface.

4. (Currently Amended) The process ~~Process~~ according to claim 1, wherein the electronic component is made up of a chip provided with contacts on one of ~~its~~ the faces of the chip, said contacts being ~~set off~~ provided on a conductive film constituting the contact areas that extend the contacts of the chip.

5. (Currently Amended) The process ~~Process~~ according to claim 1, wherein the electronic component is made up of a chip provided with contacts on one of ~~its~~ the faces of the chip, said contacts being ~~set off~~ provided on a conductive film constituting the contact areas that extend the contacts of the chip, the layer of insulating material is made up of a first substrate including a

cavity in which the chip of the component is inserted, the contact areas of said component being applied against the surface of the first substrate connecting with corresponding conductive areas of a second substrate placed on the work surface.

6. (Currently Amended) The process ~~Process~~ according to claim 5, wherein the cavity of the electronic component is obtained by heating the chip of the electronic component, then ~~pushing~~ pressing said chip into the substrate so that ~~material by means of adequate tooling,~~ the contact areas of said electronic component ~~being~~ are applied against the surface of the substrate ~~(5)~~.

7. (Currently Amended) The process ~~Process~~ according to claim 1, wherein the electronic component is made up of a chip provided with ~~sensibly~~ flat contacts on one of ~~its~~ the faces of the chip.

8. (Currently Amended) The process ~~Process~~ according to claim 7, wherein the layer of insulating material is made up of a first substrate including a cavity into which the chip is inserted, the contacts of said chip showing on the surface level of the first substrate are connected with corresponding conductive areas of a second substrate placed on the work surface.

9. (Currently Amended) The process ~~Process~~ according to claim 1, wherein the cavity of the electronic component is ~~made up~~ formed by milling or by stamping a window.

10. (Currently Amended) The process ~~Process~~ according to claim 8, wherein the cavity of the chip is obtained by heating the chip of the electronic component then pressing said chip into ~~the~~

~~material of~~ the substrate ~~by means of adequate tooling~~, the contact areas of said chip showing on the surface level of the substrate.

11. (Currently Amended) The process ~~Process~~ according to claim 1, wherein the electronic component is made up of a module including a set of flat contacts on one of ~~its~~ the faces of the module and on the opposite face conductive areas linked to each contact of the set.

12. (Currently Amended) The process ~~Process~~ according to claim [[1]] 11, wherein the module is inserted into a cavity provided with a window cut into a first substrate with a thickness approximately equal to that of the module, the set of flat contacts shows on the surface level of said substrate and the conductive areas of the opposite face lean against the conductive tracks of a second substrate assembled on the first substrate.

13. (Currently Amended) The process ~~Process~~ according to claim 12, wherein at least one module or a supplementary chip is mounted in one of the substrates, said module including conductive areas connected by pressure on the corresponding conductive tracks of either of the substrates.

14. (Currently Amended) The process ~~Process~~ according to claim 13, ~~wherein it includes~~ further comprising a supplementary step of gluing and pressing the assembly formed by the superposition of the substrates.